IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information			
upplier	r Information														
ompany	name*	Company un	Company unique ID			Unique ID Authority				Response Date*					
nsemi											2024-05-02				
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-E	Env-Stewards		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
uthorized	d Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
roduct-E	Env-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr It		tem Number Mfr Item Name				Effective Date	Version	M	Manufacturing Site		Weight*	UOM	Unit Type	
		BS170-D74Z FET 60V 5.0 n		FET 60V 5.0 mOh	nOhm TO92		2024-05-02 CNF		NF	2	219.001	mg	Each		
	cturing Process Information		Terminal Base	Alloy	-STD-020 MSL	Pating	Peak Proc	ess Rody T	'emperature	May Time at Peak	Temperat	ure Numbe	er of Reflow Cyc	las	
	8 · · · · · · · · · · · · · · · · · · ·		CU Allov NA			2 Rating	Peak Process Body Temperature Max Tir			seconds		of Kenow Cyc	.103		
omments	` ′		0 0 1 222 0 y	1 1					1~	100	Jecon	<u></u>			
or more i	information regarding materia	al composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

omogeneous Material Weight Ur		Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.075 mg		Supplier	Silicon (Si)	7440-21-3		0.075	mg
Lead Frame	101.0	mg	Supplier	Silver (Ag)	7440-22-4		0.0101	mg
			Supplier	Iron (Fe)	7439-89-6		0.101	mg
			Supplier	Copper (Cu)	7440-50-8		100.8586	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0303	mg
Mold Compound-Black	112.0			Phenol Resin	proprietary data		11.2	mg
			Supplier	Carbon Black (C)	1333-86-4		1.12	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		86.24	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		13.44	mg
Plating	5.85	mg	Supplier	Tin (Sn)	7440-31-5		5.85	mg
Wire Bond - Au	0.076	mg	Supplier	Gold (Au)	7440-57-5		0.076	mg